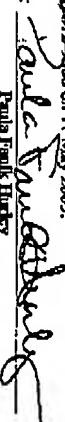


May. 12. 2005 3:33AM

No. 0174 P. 1

Application No. 106632,550  
Attorney Docket: CPAC 1017-7 DS

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Signed:   
Paula Frank Fluehr

*In THE UNITED STATES PATENT AND TRADEMARK OFFICE*

|  |                                     |
|--|-------------------------------------|
| In re application of: Marcos Kamezus   | Attorney Docket No.: CPAC 1017-7 DS |
| Application No.: 10/632,550  | Examiner: Mai-Thuong Tran           |
| Dated: 02 August 2003  | Group: 2811                         |
| Title: Semiconductor Multi-Package Module<br>Including Stacked-Die Package And Having Wire<br>Bond Interconnect Between Stacked Packages | Confirmation No.: 2570              |
|  | Customer No. 22470                  |

**INFORMATION DISCLOSURE STATEMENT AFTER ALLOWANCE**

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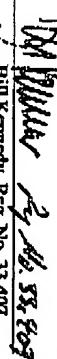
Sir:

Applicants submit the below-listed documents to be placed in the file:

- Takahashi et al., U. S. Patent No. 6,025,648 issued 15 February 2000 for "Shock Resistant Semiconductor Device and Method for Producing Same".

Respectfully submitted,  
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Date: 11 May 2005

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